PCN Number:		20131220000						PCN Date: 01/06/2014			
Title:	Title: Design Change for device CAB4AZNRR (DDR4 Register/PLL Buffer)										
Customer Contact:		PCN Manager Phone:				+1(214)480-6037		_	Quality Services		
Propose	ed 1 st Ship Da	ate:		04/06/20	014			Sample	Date provided at		
Change Type:					Availability: sample request				iple request		
		Assembly Process					Assembly Materials				
Assembly SiteAssembly ProceImage: Site systemImage: Site system				Mechanical Specification							
Test	Site	Packing/Shipping					Test Process				
Wafer Bump Site Wafer Bump Mat					Wafer Bump Process						
Wafer Fab Site Wafer Fab Mater				Wafer Fab Process							
		Part number change									
PCN Details											
Description of Change:											
This notification is to inform of a design revision for device CAB4AZNRR (DDR4 Register/PLL Buffer). This design change does not affect the device's guaranteed datasheet specifications or electrical performance. The table below describes changes that were made:											
	tion of Chang					Benefit of Ch					
	esistance (Ron) offset.				Calibrate to center of spec range.						
Modify Input Bus Termination			on	structu	re.	Reduce leakag	educe leakage.				
Reason for Change:											
Output resistance (Ron) and input leakage partially too high											
Anticipated impact on Form, Fit, Function, Quality or Reliability (positive / negative):											
None											
Changes to product identification resulting from this PCN:											
None											
Product Affected:											
CAB4AZNRR											
Changes to product identification resulting from this PCN:											
 Date code will be used to identify new material. All products assembled from Nov 2013 and later will be new material. 											

Qualification Data: Approved 12/17/2013							
This qualification has been specifically developed for the validation of this change. The qualification data validates that the proposed change meets the applicable released technical specifications.							
Qual Vehicle: CAB4AZNRR							
Package/Die Construction Details							
Assembly Site: Amkor K4			# Pins-Designator, Family: 253-		ZNR, FCBGA		
Fab Process: C021			Die Revision:	4A6 HVM			
Qualification: 🗌 Plan 🛛 Test Results							
Reliability Test		Conditions			Sample Size (PASS/FAIL)		
ESD HBM		+/- 1500V, 2000V			3/0		
ESD CDM		+/- 500V			3/0		
Latch-up		(pe	r JESD78)	3/0			

For questions regarding this notice, e-mails can be sent to the regional contacts shown below or to your local Field Sales Representative.

Location	E-Mail
USA	PCNAmericasContact@list.ti.com
Europe	PCNEuropeContact@list.ti.com
Asia Pacific	PCNAsiaContact@list.ti.com
Japan	PCNJapanContact@list.ti.com